AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph on page 8, lines 1-28, as follows:

Nest base assembly 200 is shown in Figure 2. Base assembly 200 provides the means to register and retain pogo pin socket 204 and provides the structural base to support and register the air cylinder and coldplate assembly with respect to the DUT. Nest base assembly 200 preferably includes pogo pin socket 204, although other LGA socket technologies are applicable, which is clamped to test board 206, also referred to herein as a "card", between backside stiffener 218 and topside clamp plate 202 using screw 216 that extend through stiffener 218, insulator 210, test board [[card]] 206, socket 204 and engage threaded holes in clamp plate 202. Backside stiffener 218 is preferably included to limit deformation of test board 206 and socket 204 under the high load required to actuate socket 204 and electrically connect the DUT and the test board 206. A G10 insulator 210 or similar material is preferably used to insulate pads and other electrically conductive features on test board 206 from backside stiffener 218, which is preferably metallic. Backside stiffener 218 also preferably includes a pair of cartridge heaters 212 which are controlled by the test control code and are used to retard backside condensation. Heaters 212 are held in place by heater retainers 214. One advantage of clamping socket 204 to test board [[card]] 206 between two semi-rigid structures (i.e., backside stiffener 218 and topside clamp plate 202) is the reduction of the effect of moisture absorption in the socket body plastic, which can distort some critical dimensions in the socket 204.